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With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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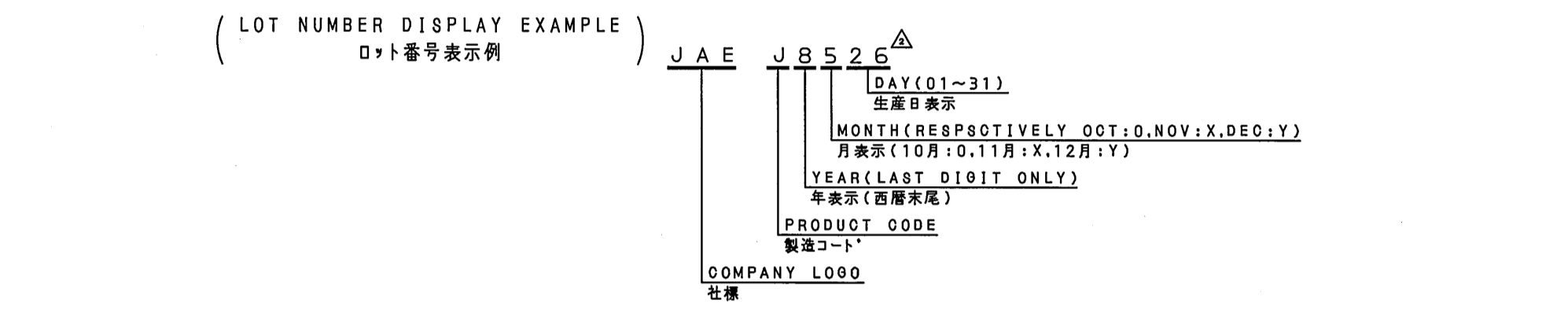
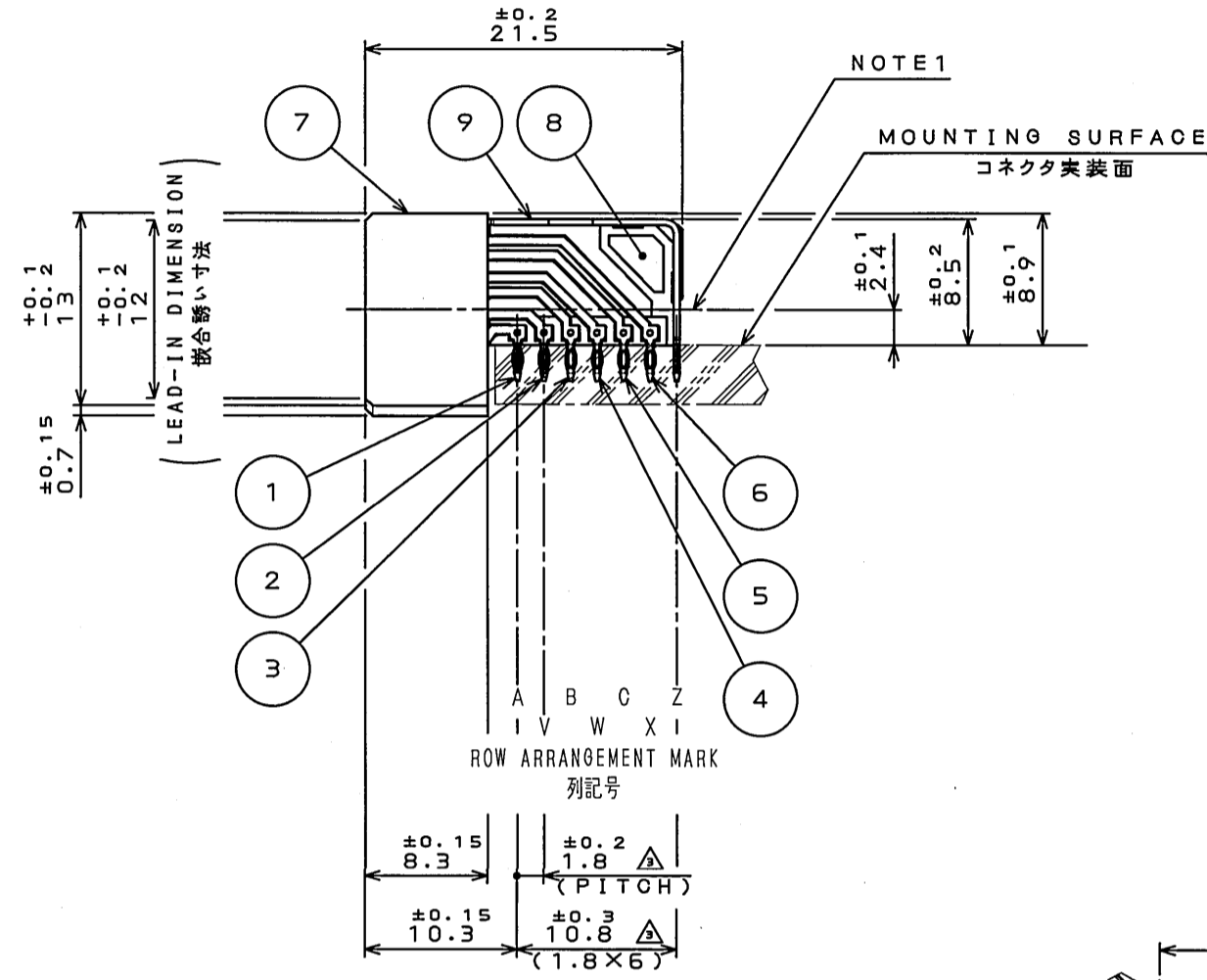
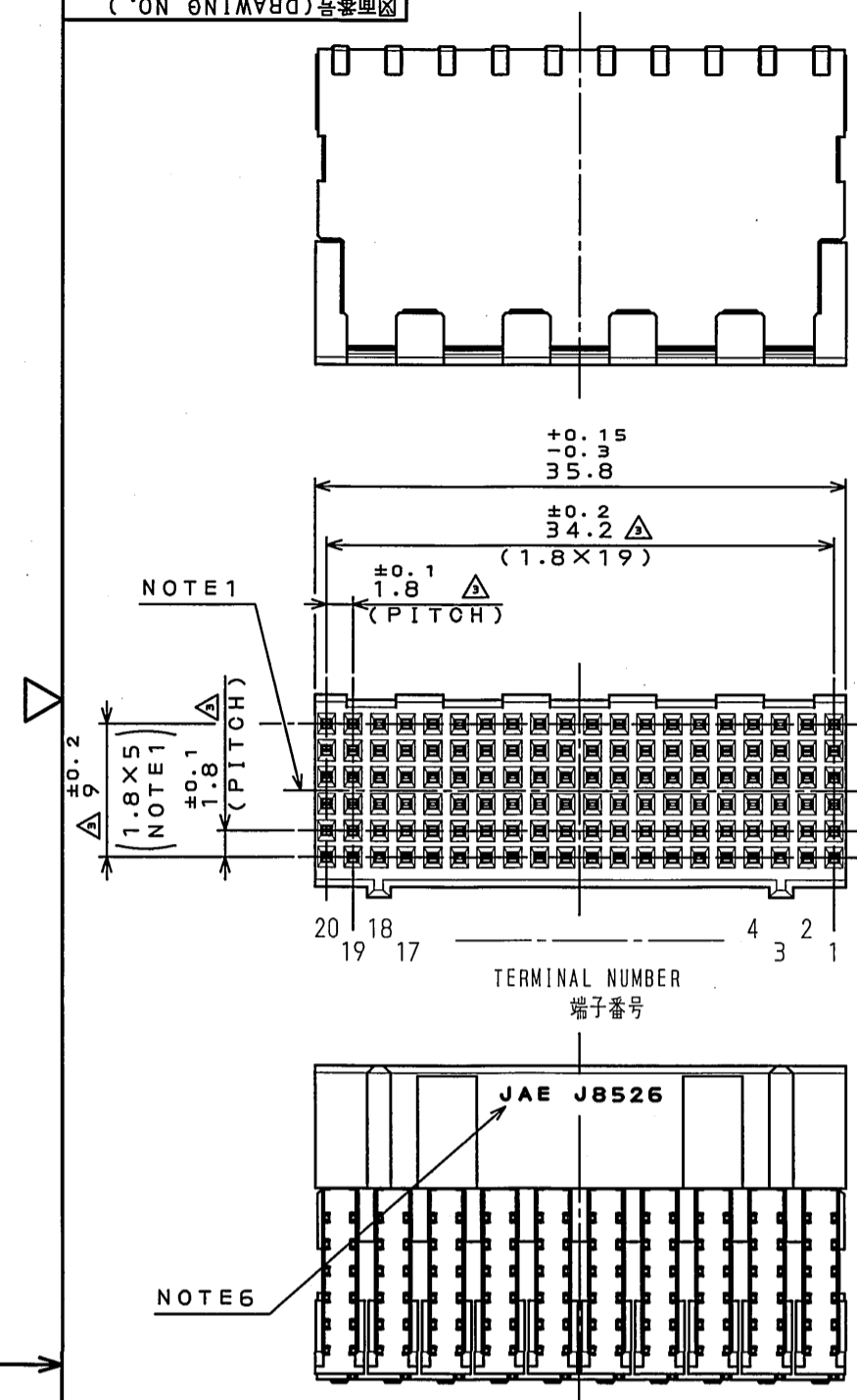
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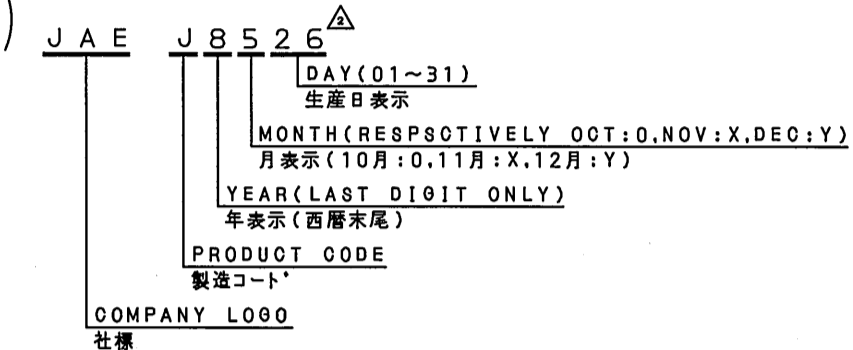


REV.	DATE	DCN NO.	DESCRIPTION	DR.	CHK.	APPD.	APPD.
2	3.Apr.2009	067684	CHANGED LOT NUMBER DISPLAY EXAMPLE.		Y.ITOU		Y.MIZUSAWA
3	29.Oct.2009	068879	DELETE "UL" NOTATION.		Y.ITOU		Y.Mizusawa

NOTE1. THIS LINE IS A CENTERLINE OF TOTAL-PITCH: 9 (1.8X5).
 2. TABLE 1 SHOWS P.C.B. THROUGH-HOLE SIZE.
 3. [Hatched Area]: CONNECTOR MOUNTING AREA (FIG.3 REF.).
 4. [Circle with slash]: THE 10 THROUGH-HOLES IN Z-ROW IS SHORT-CIRCUITED (FIG.3 REF.).
 5. PLATING THICKNESS
 CONTACT AREA : GOLD (0.1 μm MIN.) OVER NICKEL (1.5~5.0 μm) PLATING.
 PRESS-FIT AREA : GOLD (0.03 μm MIN.) OVER NICKEL (1.5~5.0 μm) PLATING.
 6. COMPANY LOGO "JAE" AND PRODUCTION LOT NUMBER AS INDICATED.



7. NOTE IT IN DIRECTION OF THE CONNECTOR (FIG.2 REF.).
 注1. 寸法9 (1.8X5)の中心線を示す。
 2. スルーホール仕様をTABLE 1に示す。
 3. [Hatched Area]はコネクタ実装領域を示す (FIG.3 参照)。
 4. [Circle with slash]内のZ列のスルーホールは、コネクタ構造上同一端子である (FIG.3 参照)。
 5. めっき仕様
 接触部: ニッケル(1.5~5.0 μm)上 金めっき(0.1 μm以上)
 結線部: ニッケル(1.5~5.0 μm)上 金フラッシュめっき(0.03 μm以上)
 6. 図示の位置に社標、ロット番号を表示する。
 7. 図示のカ'イト'に沿って、嵌合すること (FIG.2 参照).



MJ06-120FRP

TERMINATION STYLE 結線方式	P: PRESS-FIT P: プレスフィット
H: HARNESS H: ハーネス	
CONNECTING DIRECTION 接続方向	R: RIGHT-ANGLE R: ライトアング'ル
S: STRAIGHT S: ストレート	
PRODUCT TYPE 製品形態	F: SOCKET-CONTACT F: ソケットコンタクト
M: PIN-CONTACT M: ピンコンタクト	
S: SHROUD S: シュラウド	
C: HARNESS-CLIP C: ハーネスクリップ	

NUMBER OF CONTACTS 芯数

SERIES シリーズ名

DESIGNATION 命名法

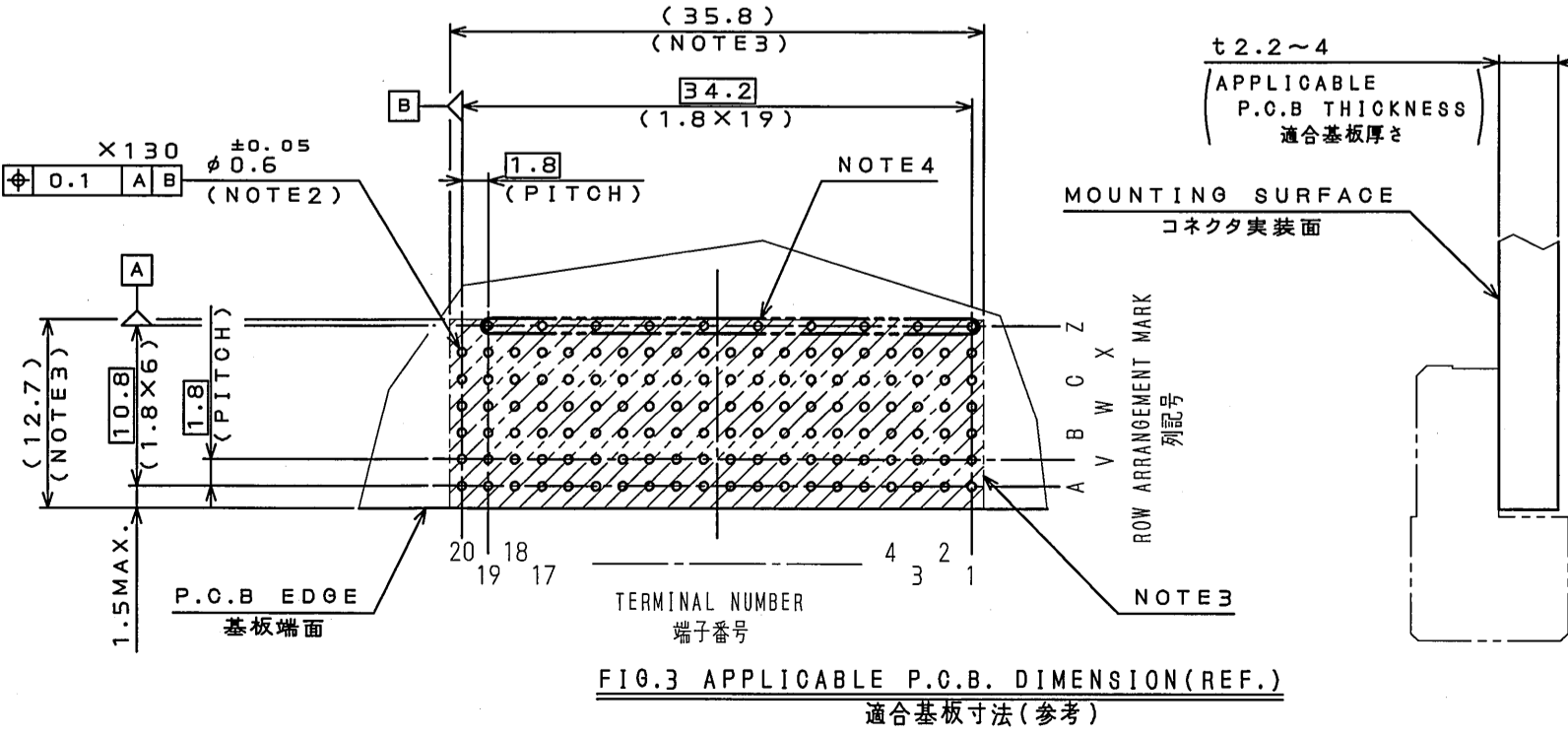
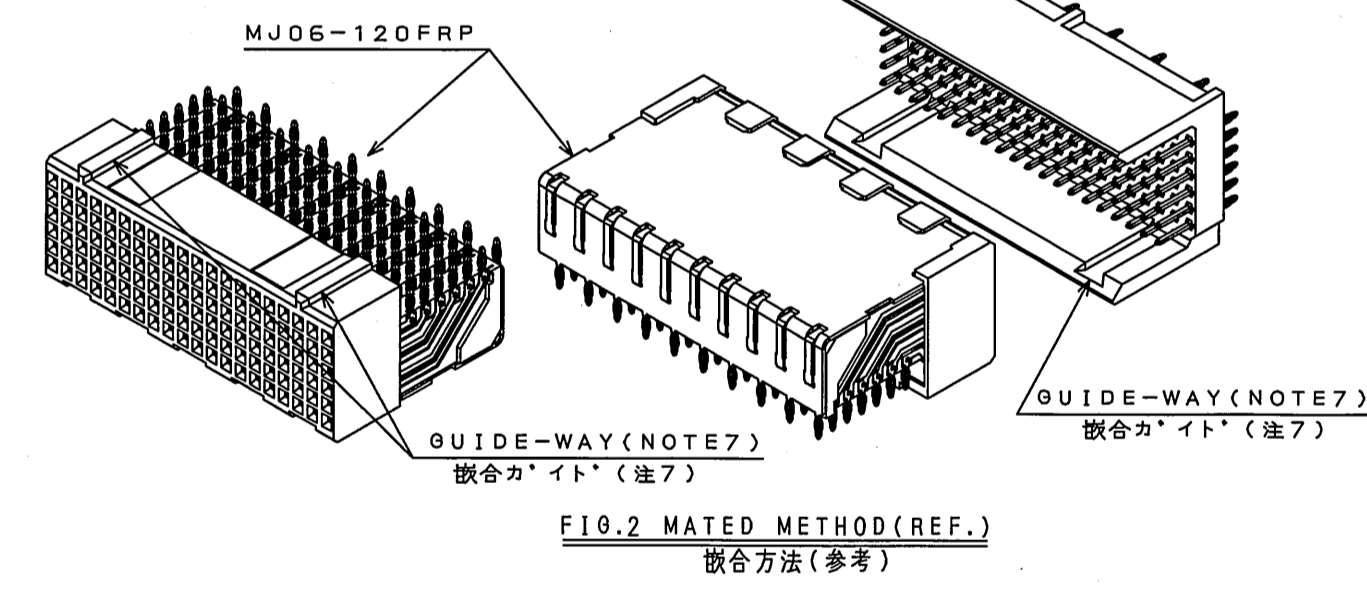
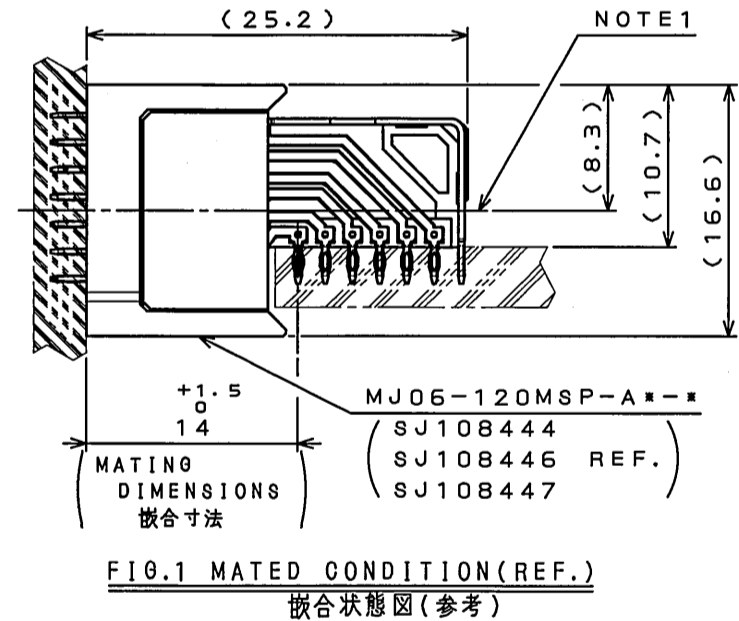


TABLE 1 P.C.B. THROUGH-HOLE SIZE (REF.)
基板スルーホール寸法 (参考)

FINISHED HOLE DIAMETER (GOLD OVER COPPER PLATING) 仕上り径 (銅上Auフラッシュめっき)	±0.05 φ0.6 [mm]
STARTED DRILL DIAMETER トリル下穴径	±0.025 φ0.7 [mm]
COPPER PLATING THICKNESS 銅めっき厚	20 [μm] MIN.
P.C.B. MATERIAL 基板材料	GLASS FILLED EPOXY カ'ラス布入りエポキシ積層板

QTY.	MATERIAL	FINISH	REMARKS
9	SHIELD-PLATE	1 COPPER ALLOY	NOTE5
8	UNIT-INSULATOR	10 GLASS FILLED PBT	COLOR: WHITE Δ
7	FRONT-INSULATOR	1 GLASS FILLED PBT	COLOR: WHITE Δ
6	CONTACT6	20 COPPER ALLOY	NOTE5
5	CONTACT5	20 COPPER ALLOY	NOTE5
4	CONTACT4	20 COPPER ALLOY	NOTE5
3	CONTACT3	20 COPPER ALLOY	NOTE5
2	CONTACT2	20 COPPER ALLOY	NOTE5
1	CONTACT1	20 COPPER ALLOY	NOTE5

仕様書 (SPECIFICATION) JACS-10524 第1版 (ORIGINAL DATE) 26.May.2008 図面 (SCALE) 2:1 シリーズ (SERIES) MJ06 日本航空電子工業株式会社

製造 DR. 担当 CHK. Y.ITOU 名称 (TITLE) MJ06-120FRP JAPAN AVIATION ELECTRONICS INDUSTRY, LTD.

公差 (GENERAL TOLERANCE) 寸法 (DIMENSION) 角度 (ANGLES) 承認 APPD. Y.MIZUSAWA 数量 (MASS) 15.8[g]

図面番号 (DRAWING NO.) SJ108443 版数 (REV.) 3